



TEP-1010-IMX6 MODULAR HMI PRODUCT MANUAL
(TEP-1010-IMX6)

VER. 1.01

February 27, 2019

REVISION HISTORY

| Revision | Date | Originator | Notes |
|----------|-------------------|------------|-----------------------|
| 1.00 | August 21, 2018 | TechNexion | First public release |
| 1.01 | February 27, 2019 | TechNexion | Ordering table update |

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1. Introduction

1.1. General Care and Maintenance

Your device is a product of superior design and craftsmanship and should be treated with care.

The following suggestions will help you.

- Keep the device dry. Precipitation, humidity, and all types of liquids or moisture can contain minerals that will corrode electronic circuits. If your device does get wet, allow it to dry completely.
- Do not use or store the device in dusty or dirty areas. Its parts and electronic components can be damaged.
- Do not store the device in hot areas. High temperatures can shorten the life of electronic devices, damage batteries, and warp or melt certain plastics.
- Do not store the device in cold areas. When the device returns to its normal temperature, moisture can form inside the device and damage electronic circuit boards.
- Do not open the device while power is on. Otherwise electrical shock may result.
- Do not drop, knock, or shake the device. Rough handling can break internal circuit boards and fine mechanics.
- Do not use harsh chemicals, cleaning solvents, or strong detergents to clean the device.
- Do not paint the device. Paint can clog the parts and prevent proper operation.
- Unauthorized modifications or attachments could damage the device and may violate regulations governing radio devices.

These suggestions apply equally to your device, battery, charger, or any enhancement. If any device is not working properly, take it to the nearest authorized service facility for service.

Regulatory information



Disposal of Waste Equipment by Users in Private Household in the European Union
This symbol on the product or on its packaging indicates that this product must not be disposed of with your other household waste. Instead, it is your responsibility to dispose of your waste equipment by handing it over to a designated collection point for the recycling of waste electrical and electronic equipment. The separate collection and recycling of your waste equipment at the time of disposal will help to conserve natural resources and ensure that it is recycled in a manner that protects human health and the environment. For more information about where you can drop off your waste equipment

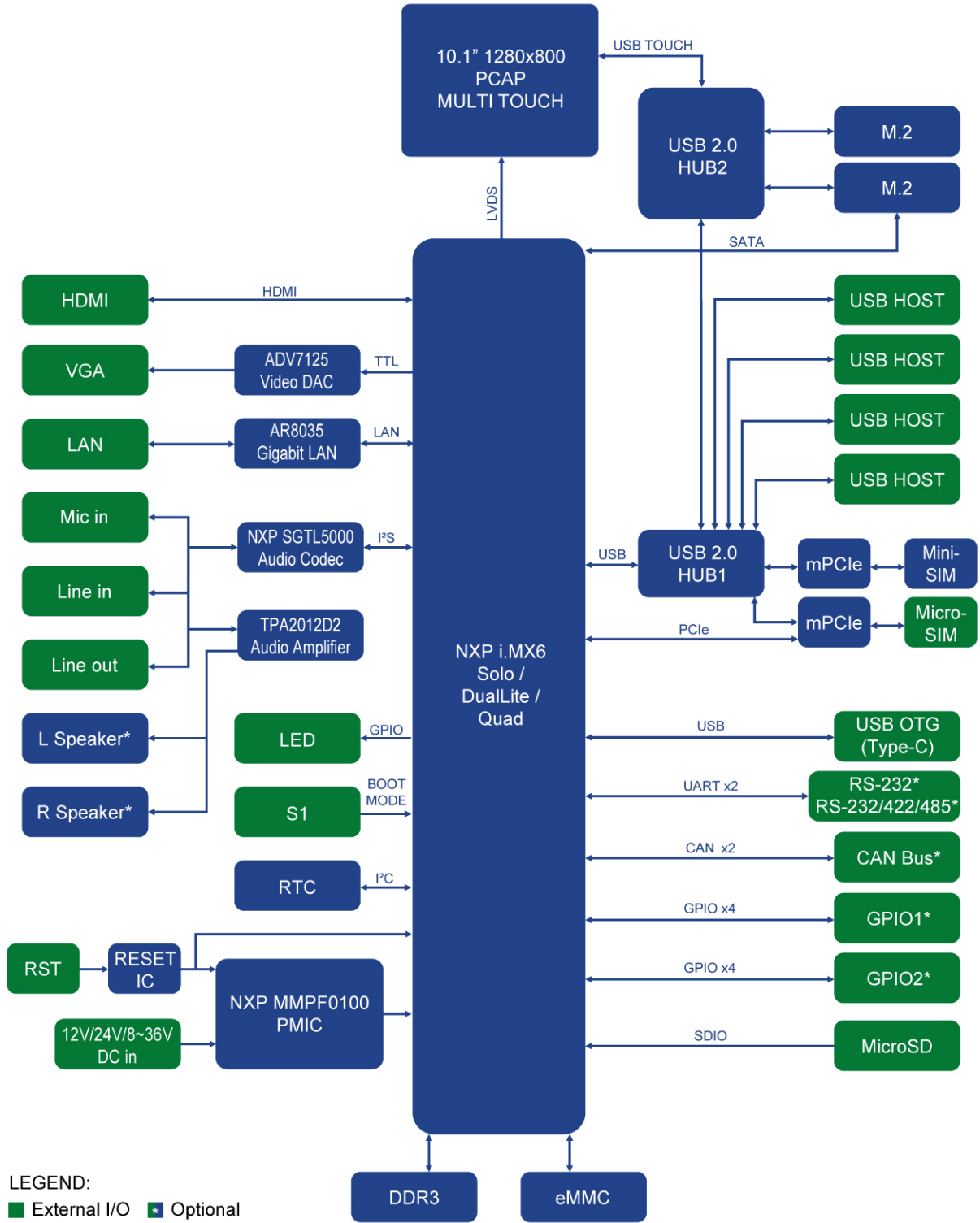
for recycling, please contact your local city office, your household waste disposal service or the shop where you purchased the product.



We hereby declare that the product is in compliance with the essential requirements and other relevant provisions of European Directive 2014/53/EU (Directive on the harmonisation of the laws of the Member States relating to the making available on the market of radio equipment and repealing Directive 1999/5/EC).

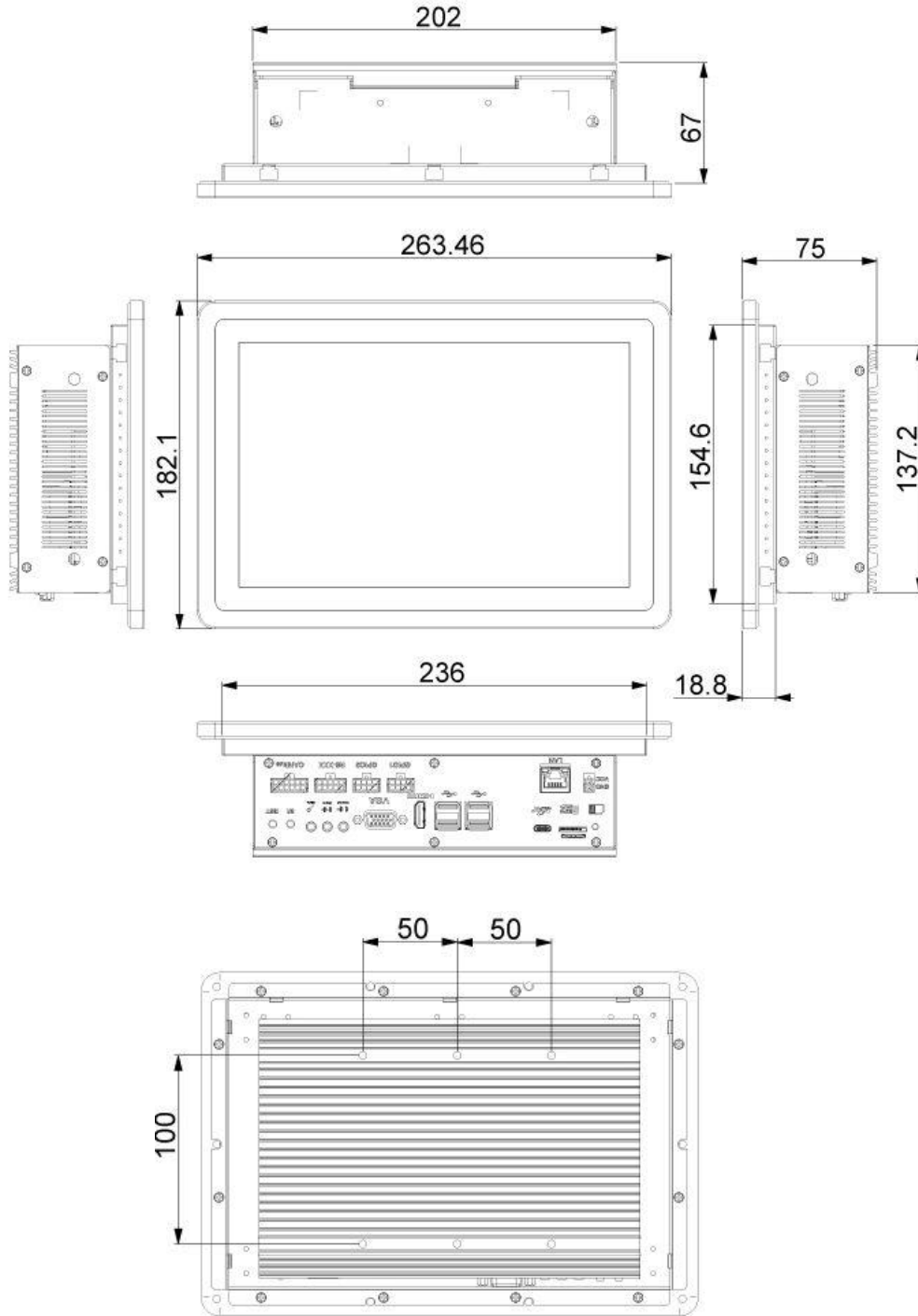
2. TEP-1010-IMX6 Product Overview

2.1. Functional Block Diagram



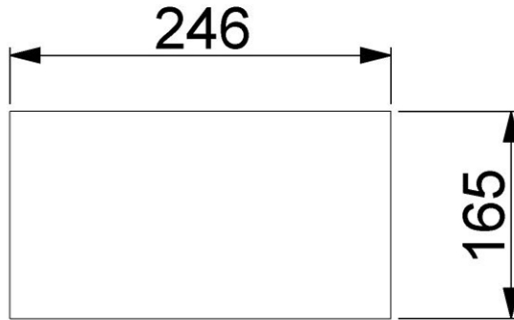
2.2. Dimensions

The following figure shows the TEP-1010-IMX6 dimensions (unit: mm):



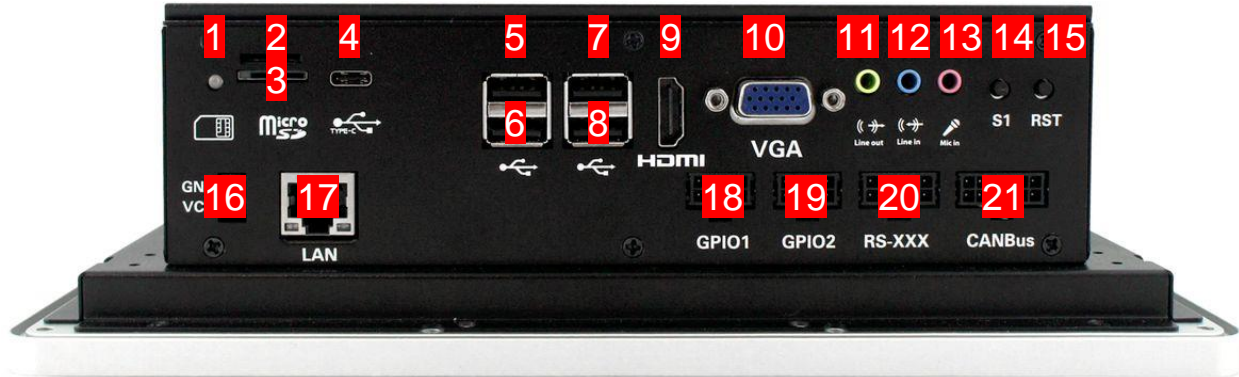
2.3. Device Cut-out Dimensions For Mounting Through a Panel

The TEP-1010-IMX6 can be mounted on the front or the back of the panel. In order to mount it from the front, a nominal rectangular cutout must be made in the panel. The following drawing shows the dimensions of the cut-out area (unit: mm):



2.4. External Connectors

The TEP-1010-IMX6 has a number of external connectors.
Bottom view:



External Connectors:

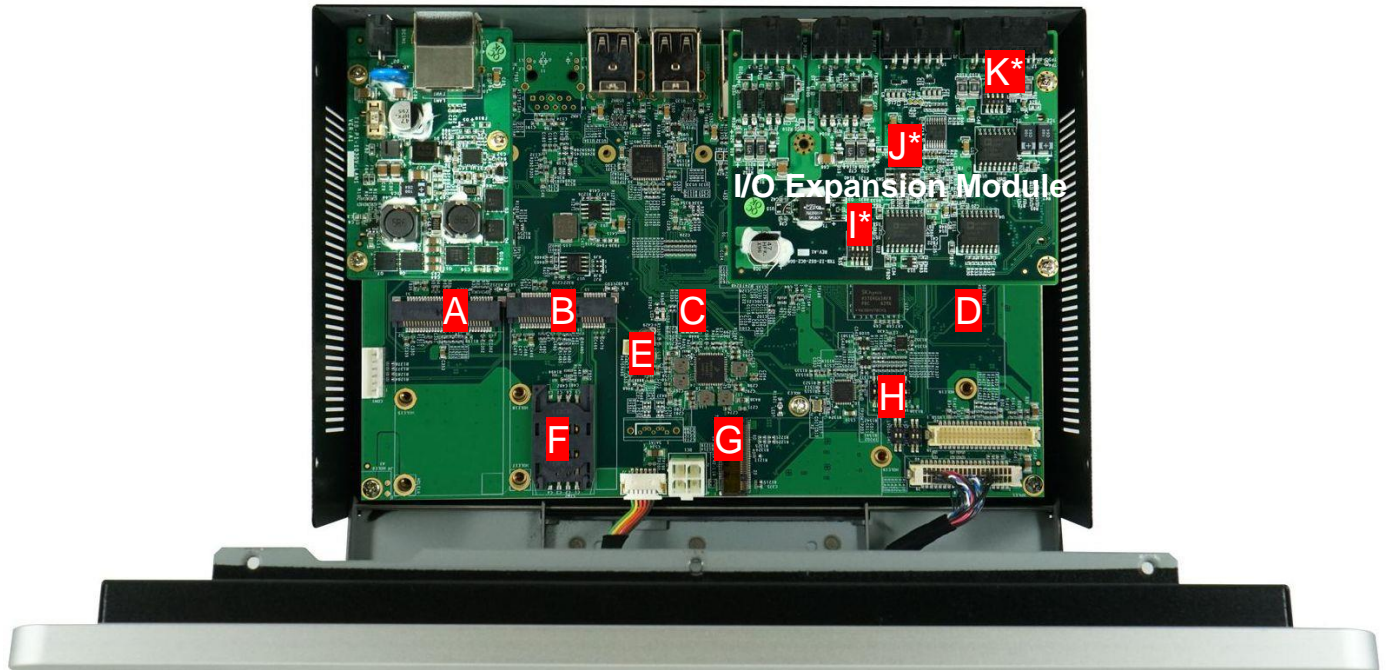
| No. | Description | No. | Description |
|-----|------------------------------|-----|---|
| 1 | LED Light indicator | 12 | 3.5mm jack Line in |
| 2 | Micro-SIM card slot | 13 | 3.5mm jack Mic in |
| 3 | MicroSD card slot | 14 | S1 Boot Select button |
| 4 | USB OTG (Type-C) connector | 15 | Reset button |
| 5 | USB Host connector | 16 | Power Input connector |
| 6 | USB Host connector | 17 | LAN RJ45 connector |
| 7 | USB Host connector | 18 | GPIO1 connector (optional) |
| 8 | USB Host connector | 19 | GPIO2 connector (optional) |
| 9 | HDMI connector | 20 | RS-XXX (Serial Port) connector (optional) |
| 10 | VGA (15-pin D-SUB) connector | 21 | CAN Bus connector (optional) |
| 11 | 3.5mm jack Line out | | |

2.5. Internal Board Connectors

The TEP-1010-IMX6 has several connectors, switches and internal expansion options.

2.5.1. Galvanic Isolated (TEP1010-IMX6x-Rxx-Exx-Lxxx-XG20-xxx-xxxx)

Rear view (opened device) with the galvanic isolated I/O Expansion module:



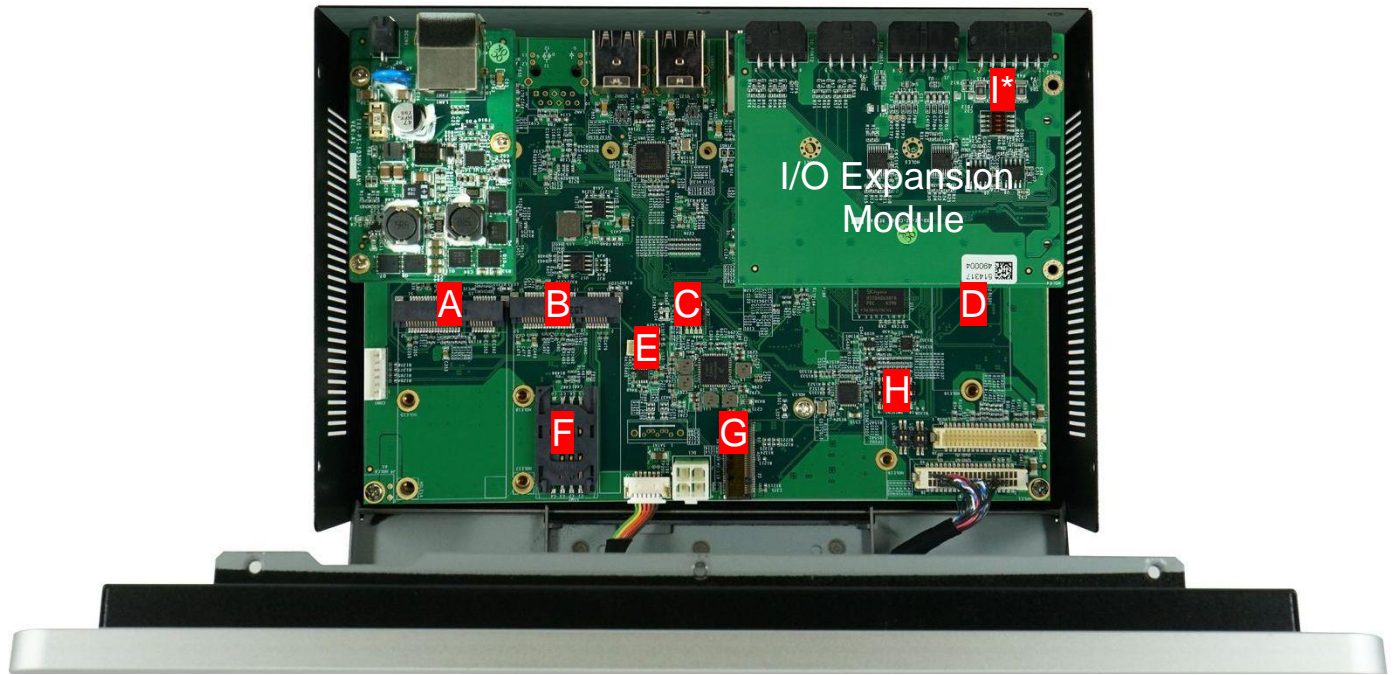
Internal Connectors and Switches:

| No. | Description | No. | Description |
|-----|----------------------------------|-----|------------------------------------|
| A | mini-PCIe connector (PCIe + USB) | G | M.2 KEY-B slot (SATA + USB) |
| B | mini-PCIe connector (USB) | H | SWITCH1 Boot mode DIP switch |
| C | SW2 Default Boot mode switch | I* | SW1 DIP switch |
| D | M.2 KEY-B slot (USB) | J* | SW3 Terminator Resistor DIP switch |
| E | RTC Battery connector | K* | SW2 Terminator Resistor DIP switch |
| F | Mini-SIM card slot | | |

NOTE: Items marked with * are available on the galvanic isolated I/O Expansion module (TXB-I2-GS2-GC2-GG8) (optional).

2.5.2. Non-Galvanic Isolated (TEP1010-IMX6x-Rxx-Exx-Lxxx-**XS20**-xxx-xxxx)

Rear view (opened device) with the non-galvanic isolated I/O Expansion module:



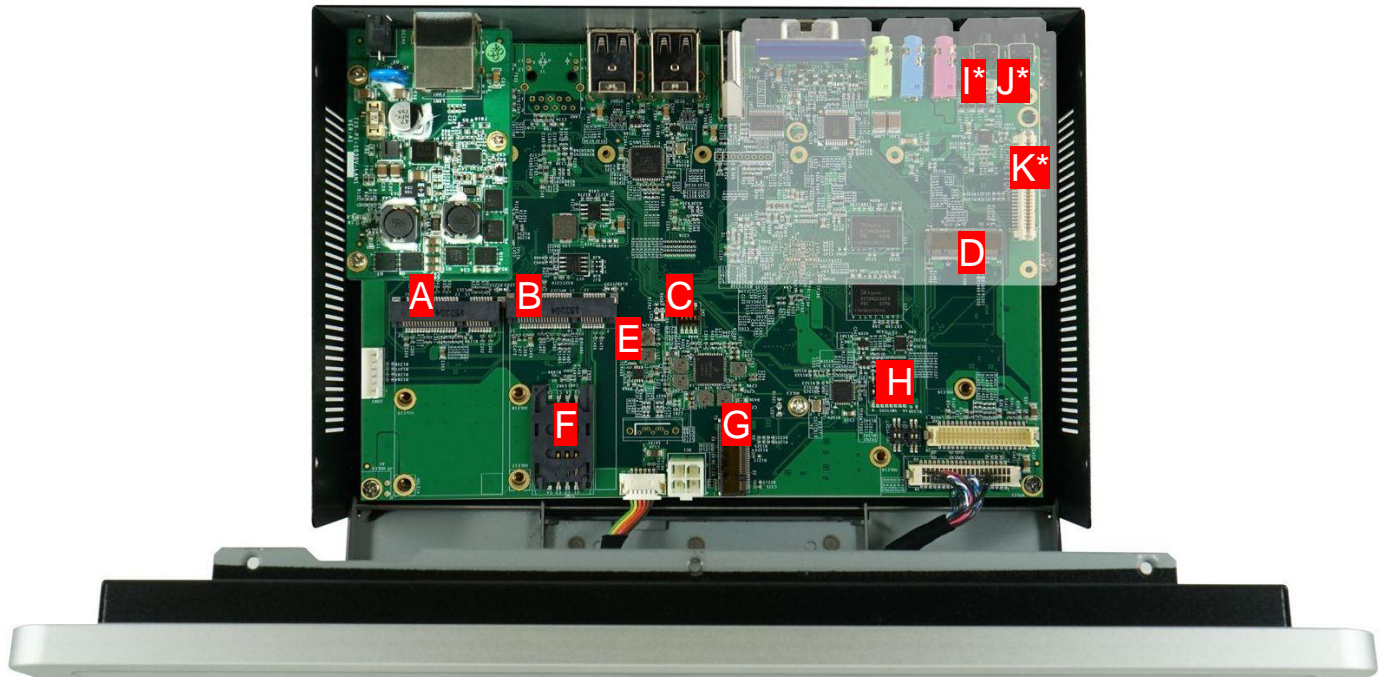
Internal Connectors and Switches:

| No. | Description | No. | Description |
|-----|----------------------------------|-----|------------------------------------|
| A | mini-PCIe connector (PCIe + USB) | F | Mini-SIM card slot |
| B | mini-PCIe connector (USB) | G | M.2 KEY-B slot (SATA + USB) |
| C | SW2 Default Boot mode switch | H | SWITCH1 Boot mode DIP switch |
| D | M.2 KEY-B slot (USB) | I* | SW1 Terminator Resistor DIP switch |
| E | RTC Battery connector | | |

NOTE: Items marked with * are available on the non-galvanic isolated I/O Expansion module (TXB-I2-S2-C2-G8) (optional).

2.5.3. Board View Without the I/O Expansion Module

Rear view (opened device) without the I/O Expansion module:



Internal Connectors and Switches:

| No. | Description | No. | Description |
|-----|----------------------------------|-----|--------------------------------|
| A | mini-PCIe connector (PCIe + USB) | G | M.2 KEY-B slot (SATA + USB) |
| B | mini-PCIe connector (USB) | H | SWITCH1 Boot mode DIP switch |
| C | SW2 Default Boot mode switch | I* | Internal R speaker connector |
| D | M.2 KEY-B slot (USB) | J* | Internal L speaker connector |
| E | RTC Battery connector | K* | I/O Expansion module connector |
| F | Mini-SIM card slot | | |

NOTE: Items marked with * are accessible only after removing the I/O Expansion module.

3. External Connectors

3.1. LED Light Indicator

The TEP-1010-IMX6 has one programmable LED Light indicator.

| LED # | Color | GPIO Kernel | GPIO Bank/IO |
|-------|-------|-------------|--------------|
| 1 | Green | 9 | 1_9 |

3.2. Micro-SIM Card Slot

The TEP-1010-IMX6 features an external Micro-SIM card slot for use by 3G/4G/LTE wireless module.

NOTE: This card slot can be only used by a mini-PCIe 3G/4G/LTE module installed into the MPCIE1 connector. The MPCIE1 connector can be found at location “A” in chapter [4. Internal Connectors and Expansion Options](#) of this manual. No mini-PCIe 3G/4G LTE module is included in this device (must be purchased separately, not sold by TechNexion).

3.3. MicroSD Card Slot

The TEP-1010-IMX6 features a standard microSD card slot which is connected to the NXP i.MX6 integrated “Ultra Secured Digital Host Controller” (uSDHC).

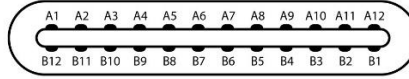
The following main features are supported by uSDHC:

- Compatible with the MMC System Specification version 4.2/4.3/4.4/4.41/5.0.
- Conforms to the SD Host Controller Standard Specification version 3.0.
- Compatible with the SD Memory Card Specification version 3.0 and supports the “Extended Capacity SD Memory Card”.
- Compatible with the SDIO Card Specification version 3.0.
- Supports 1-bit / 4-bit SD and SDIO modes

The MMC/SD/SDIO host controller can support a single MMC / SD / SDIO card or device.

3.4. USB OTG (Type-C) Connector

The TEP-1010-IMX6 has one USB Type-C connector (USB 2.0 signals only) that can be used to connect a host computer to the unit for programming and update purposes.



| Pin # | Signal | Description | Pin # | Signal | Description |
|-------|--------|-------------------------------------|-------|--------|-------------------------------------|
| A1 | GND | Ground | B1 | GND | Ground |
| A2 | NC | | B2 | NC | |
| A3 | NC | | B3 | NC | |
| A4 | VBUS | 5V Universal Serial Bus Power | B4 | VBUSD | 5V Universal Serial Bus Power |
| A5 | CC1 | OTG detection signal | B5 | CC2D | OTG detection signal |
| A6 | USB_D+ | USB differential pair signal port 1 | B6 | USB_D+ | USB differential pair signal port 2 |
| A7 | USB_D- | | B7 | USB_D- | |
| A8 | NC | | B8 | NC | |
| A9 | VBUS | 5V Universal Serial Bus Power | B9 | VBUSD | 5V Universal Serial Bus Power |
| A10 | NC | | B10 | NC | |
| A11 | NC | | B11 | NC | |
| A12 | GND | Ground | B12 | GND | Ground |

3.5. USB Host Connector

The TEP-1010-IMX6 has four USB Host connectors (USB 2.0 signals only) to connect to a USB peripheral such as a keyboard, mouse, USB storage device or USB hub.

3.6. HDMI (High Definition Multi-Media Interface) Connector

The HDMI interface available on the TEP-1010-IMX6 is based on the “HDMI transmitter” & “HDMI 3D TX PHY” integrated into the NXP i.MX6 processor and can be configured to support a secondary display.

The HDMI supports the following standards & features:

- High-Definition Multimedia Interface Specification, Version 1.4a
- Digital Visual Interface, Revision 1.0
- HDMI Compliance Test Specification, Version 1.4a
- Support for up to 720p at 100Hz and 720i at 200Hz or 1080p at 60Hz and 1080i/720i at 120Hz HDTV display resolutions and up to QXGA graphic display resolutions.
- Support for 4k x 2k and 3D video formats
- Support for up to 16-bit Deep Color modes

3.7. VGA (15-pin D-SUB) Connector

The VGA interface available on the TEP-1010-IMX6 can be configured to support a secondary display.

3.8. Audio Connectors

The TEP-1010-IMX6 has three external 3.5mm stereo audio jacks.

| Color Code | Signal | Description |
|------------|--------------|------------------|
| Green | L/R Line out | Audio output |
| Blue | L/R Line in | Audio input |
| Pink | Mic in | Microphone input |

3.9. S1 Button

The TEP-1010-IMX6 by default boots the unit from internal flash storage (eMMC). By pressing the “S1” button before applying power to the unit and keeping the button pressed for 10 seconds, the unit will boot from an alternative boot media, such as a microSD card. The primary and alternative boot media are determined by internal DIP switch settings. Please see sections [4.4. SW2 Default Boot Mode Switch](#) and [4.5. SWITCH1 Boot Mode DIP Switch](#) for more details.

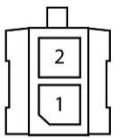
3.10. RST Button

The TEP-1010-IMX6 features a “RST” button for system reset.

3.11. Power Input Connector

The TEP-1010-IMX6 can be powered either over the DC INPUT connector or PoE (optional) over the RJ45 LAN port.

NOTE: Do not power the unit by DC input when you apply power over the Power over Ethernet (RJ45)!



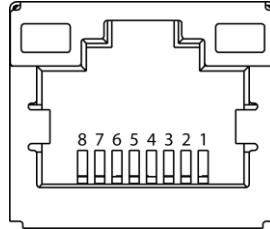
| Pin # | Signal | Description |
|-------|--------|------------------------------------|
| 1 | GND | Ground |
| 2 | VCC | DC Voltage input (12V/24V/8~36VDC) |

Header on TEP-1010-IMX6: Molex 43045-0200 (2-pin Micro-Fit 3.0).

Cable receptacle: Molex 43025-0200 (2-pin Micro-Fit 3.0) plug with crimp contact Molex 43030-0007.

3.12. Gigabit Ethernet Interface

The TEP-1010-IMX6 by default comes with a single Gigabit Ethernet RJ45 connector. This connector can support 802.3at Power over Ethernet functionality if configured with the PoE power option (TEP1010-IMX6x-Rxx-Exx-**LPOE**-Xxxx-xxx-xxxx) by connecting it to an 802.3at compliant PoE switch or power injector.



| Pin # | 1000 Mbps | 100 Mbps | 10 Mbps |
|-------|-----------|----------------|----------------|
| 1 | MDI0+ | Transmit Data+ | Transmit Data+ |
| 2 | MDI0- | Transmit Data- | Transmit Data- |
| 3 | MDI1+ | Receive Data+ | Receive Data+ |
| 4 | MDI2+ | | |
| 5 | MDI2- | | |
| 6 | MDI1- | Receive Data- | Receive Data- |
| 7 | MDI3+ | | |
| 8 | MDI3- | | |

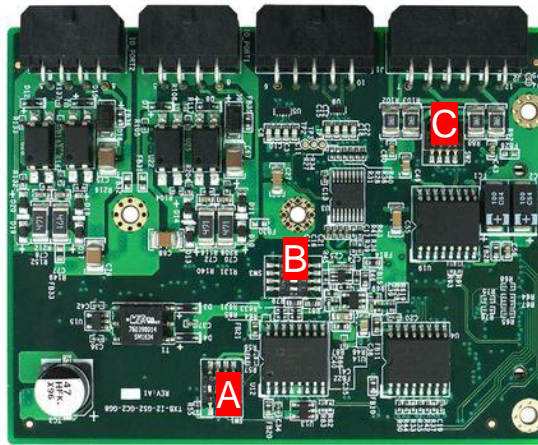
3.13. Antenna Holes

There are six antenna holes available (two each on the left side, on the right side and on the top side). They come fitted with breakaway metal tabs. In order to utilize them, the tabs must be removed by carefully using pincers or pliers.

3.14. Galvanic Isolated Connectors (TEP1010-IMX6x-Rxx-Exx-Lxxx-XG20-xxx-xxxx) (optional)

This product is available with four optional connectors: GPIO1, GPIO2, RS-XXX and CAN Bus that can be ordered in either galvanic isolated or non-galvanic isolated versions. The TEP1010-IMX6x-Rxx-Exx-Lxxx-XG20-xxx-xxxx has four optional galvanic isolated connectors: GPIO1, GPIO2, RS-XXX and CAN Bus.

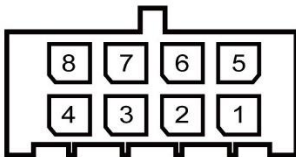
Top view of the galvanic isolated I/O Expansion module (TXB-I2-GS2-GC2-GG8):



| No. | Description | No. | Description |
|-----|------------------------------------|-----|------------------------------------|
| A | SW1 DIP switch | C | SW2 Terminator Resistor DIP switch |
| B | SW3 Terminator Resistor DIP switch | | |

3.14.1. Galvanic Isolated Digital I/O Connectors (GPIO1/GPIO2) (optional)

The galvanic isolated GPIO Expansion headers have the following pinout:



GPIO1:

| Pin # | Signal | Description | Voltage | | | Current Max. | GPIO Kernel | GPIO Bank/IO |
|-------|---------|------------------------------|---------|------|------|--------------|-------------|--------------|
| | | | Min. | Typ. | Max. | | | |
| 1 | GPIO1A | DIG_IN1 | | | 6V | 1A | 161 | 6_1 |
| 2 | GPIO1B | DIG_IN2 | | | 6V | 1A | 42 | 2_10 |
| 3 | GND_DIO | Ground for digital I/O | | | | | | |
| 4 | GND | Common Ground | | | | | | |
| 5 | GPIO1C | DIG_OUT5 | | | 16V | 1.7A | 1 | 1_1 |
| 6 | GPIO1D | DIG_OUT6 | | | 16V | 1.7A | 102 | 4_6 |
| 7 | VCC_DIO | Supply input for digital I/O | | | 16V | | | |
| 8 | VCC | Supply output | | 12V | | | | |

GPIO2:

| Pin # | Signal | Description | Voltage | | | Current Max. | GPIO Kernel | GPIO Bank/IO |
|-------|---------|------------------------------|---------|------|------|--------------|-------------|--------------|
| | | | Min. | Typ. | Max. | | | |
| 1 | GPIO2A | DIG_IN1 | | | 6V | 1A | 165 | 6_5 |
| 2 | GPIO2B | DIG_IN2 | | | 6V | 1A | 164 | 6_4 |
| 3 | GND_DIO | Ground for digital I/O | | | | | | |
| 4 | GND | Common Ground | | | | | | |
| 5 | GPIO2C | DIG_OUT5 | | | 16V | 1.7A | 162 | 6_2 |
| 6 | GPIO2D | DIG_OUT6 | | | 16V | 1.7A | 163 | 6_3 |
| 7 | VCC_DIO | Supply input for digital I/O | | | 16V | | | |
| 8 | VCC | Supply output | | 12V | | | | |

Header on TEP-1010-IMX6: Molex 43045-0800 (8-pin Micro-Fit 3.0).

Cable receptacle: Molex 43025-0800 (8-pin Micro-Fit 3.0) plug with crimp contact Molex 43030-0007.

3.14.2. Galvanic Isolated Serial Port (RS-XXX) (optional)

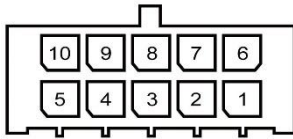
The dual 4-wire galvanic isolated serial port can be configured as follows: the primary serial port can only be used as a standard RS-232. The secondary port can be configured either as RS-232, or RS-422 or RS-485. This serial port is set by default as RS-232. Setting the TEP-1010-IMX6 in other mode will require to open the device and adjust the internal SW1 DIP and SW3 Terminator Resistor DIP switch settings on the TEP I/O Expansion board. The SW1 DIP switch can be found at location “A” and SW3 DIP switch at location “B” in chapter [3.14. Galvanic Isolated Connectors \(TEP1010-IMX6x-Rxx-Exx-Lxxx-XG20-xxx-xxxx\) \(optional\)](#) of this manual.

SW1:

| Pin # | RS-232 (default) | RS-422 | RS-485 |
|-------|------------------|--------|--------|
| 1-8 | ON | OFF | OFF |
| 2-7 | OFF | ON | OFF |
| 3-6 | OFF | OFF | ON |
| 4-5 | - | - | - |

SW3:

| Pin # | ON | OFF |
|-------|-----------------------------------|------------------------------------|
| 1-8 | Enable RS-485 Terminator Resistor | Disable RS-485 Terminator Resistor |
| 2-7 | Enable RS-422 Terminator Resistor | Disable RS-422 Terminator Resistor |
| 3-6 | - | - |
| 4-5 | - | - |



RS-232 + RS-232 (default setup):

| Pin # | Signal | Description | Device |
|-------|--------------|----------------------------------|---------|
| 1 | GND | Ground | |
| 2 | SERIAL1A_TXD | Port#1A Transmit data (output) | ttymxc0 |
| 3 | SERIAL1A_RXD | Port#1A Receive data (input) | ttymxc0 |
| 4 | SERIAL1A_RTS | Port#1A Request-to-send (output) | ttymxc0 |
| 5 | SERIAL1A_CTS | Port#1A Clear-to-send (input) | ttymxc0 |
| 6 | GND | Ground | |
| 7 | SERIAL1B_TXD | Port#1B Transmit data (output) | ttymxc1 |
| 8 | SERIAL1B_RXD | Port#1B Receive data (input) | ttymxc1 |
| 9 | SERIAL1B_RTS | Port#1B Request-to-send (output) | ttymxc1 |
| 10 | SERIAL1B_CTS | Port#1B Clear-to-send (input) | ttymxc1 |

RS-232 + RS-422:

| Pin # | Signal | Description | Device |
|-------|---------------|---|---------|
| 1~5 | SERIAL1A | Identical as above | ttymxc0 |
| 6 | GND | Ground | |
| 7 | SERIAL1B_TXD+ | RS-422 Transmit positive data signal (output) | ttymxc1 |
| 8 | SERIAL1B_RXD- | RS-422 Receive negative data signal (input) | ttymxc1 |
| 9 | SERIAL1B_RXD+ | RS-422 Receive positive data signal (input) | ttymxc1 |
| 10 | SERIAL1B_TXD- | RS-422 Transmit negative data signal (output) | ttymxc1 |

RS-232 + RS-485:

| Pin # | Signal | Description | Device |
|-------|-----------|-----------------------------|---------|
| 1~5 | SERIAL1A | Identical as above | ttymxc0 |
| 6 | GND | Ground | |
| 7 | SERIAL1B+ | RS-485 positive data signal | ttymxc1 |
| 8 | NC | | |
| 9 | NC | | |
| 10 | SERIAL1B- | RS-485 negative data signal | ttymxc1 |

NOTE: SERIAL1A port can act by default as serial debug console.

Header on TEP-1010-IMX6: Molex 43045-1000 (10-pin Micro-Fit 3.0).

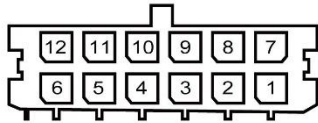
Cable receptacle: Molex 43025-1000 (10-pin Micro-Fit 3.0) plug with crimp contact Molex 43030-0007.

3.14.3. Galvanic Isolated CAN Bus Connector (CANBus) (optional)

The galvanic isolated CAN Bus interfaces can be configured as follows: enabling or disabling of CAN Bus terminator resistor will require to open the device and adjust the internal SW2 Terminator Resistor DIP switch settings on the TEP I/O Expansion board. The SW2 DIP switch can be found at location “C” in chapter [3.14. Galvanic Isolated Connectors \(TEP1010-IMX6x-Rxx-Exx-Lxxx-XG20-xxx-xxxx\) \(optional\)](#) of this manual.

SW2:

| Pin # | ON | OFF (default) |
|-------|----------------------------------|-----------------------------------|
| 1-8 | Enable CAN1A Terminator Resistor | Disable CAN1A Terminator Resistor |
| 2-7 | Enable CAN1A Terminator Resistor | Disable CAN1A Terminator Resistor |
| 3-6 | Enable CAN1B Terminator Resistor | Disable CAN1B Terminator Resistor |
| 4-5 | Enable CAN1B Terminator Resistor | Disable CAN1B Terminator Resistor |



CANBus:

| Pin # | Signal | Description | Interface |
|-------|--------------|--|-----------|
| 1 | GND_CAN | Ground for CAN | |
| 2 | CAN1A_TERM_N | To enable CAN1A Termination, bridge with CAN1A_N | can0 |
| 3 | CAN1A_P | CAN Bus 1A high (-24~+24V) | can0 |
| 4 | CAN1A_N | CAN Bus 1A low (-24~+24V) | can0 |
| 5 | CAN1A_TERM_P | To enable CAN1A Termination, bridge with CAN1A_P | can0 |
| 6 | NC | | |
| 7 | GND_CAN | Ground for CAN | |
| 8 | CAN1B_TERM_N | To enable CAN1B Termination, bridge with CAN1B_N | can1 |
| 9 | CAN1B_P | CAN Bus 1B high (-24~+24V) | can1 |
| 10 | CAN1B_N | CAN Bus 1B low (-24~+24V) | can1 |
| 11 | CAN1B_TERM_P | To enable CAN1B Termination, bridge with CAN1B_P | can1 |
| 12 | NC | | |

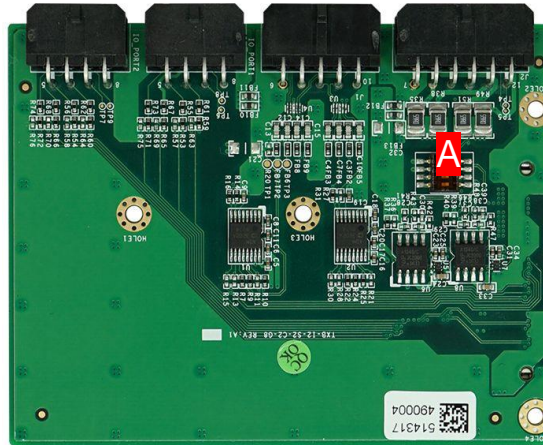
Header on TEP-1010-IMX6: Molex 43045-1200 (12-pin Micro-Fit 3.0).

Cable receptacle: Molex 43025-1200 (12-pin Micro-Fit 3.0) plug with crimp contact Molex 43030-0007.

3.15. Non-Galvanic Isolated Connectors (TEP1010-IMX6x-Rxx-Exx-Lxxx-**XS20**-xxx-xxxx) (optional)

This product is available with four optional connectors: GPIO1, GPIO2, RS-XXX and CAN Bus that can be ordered in either galvanic isolated or non-galvanic isolated versions. The TEP1010-IMX6x-Rxx-Exx-Lxxx-**XS20**-xxx-xxxx has four optional non-galvanic isolated connectors: GPIO1, GPIO2, RS-XXX and CAN Bus.

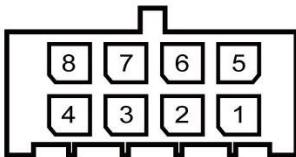
Top view of the non-galvanic isolated I/O Expansion module (TXB-I2-S2-C2-G8):



| No. | Description | No. | Description |
|-----|------------------------------------|-----|-------------|
| A | SW1 Terminator Resistor DIP switch | | |

3.15.1. Non-Galvanic Isolated Digital I/O Connectors (GPIO1/GPIO2) (optional)

The non-galvanic isolated GPIO Expansion headers have the following pinout:



GPIO1:

| Pin # | Signal | Description | Voltage | | | Current Max. | GPIO Kernel | GPIO Bank/IO |
|-------|--------|---------------|---------|------|------|--------------|-------------|--------------|
| | | | Min. | Typ. | Max. | | | |
| 1 | GPIO1A | DIG_IN1/OUT1 | 1.65V | 3.3V | 3.6V | 0.33mA | 161 | 6_1 |
| 2 | GPIO1B | DIG_IN2/OUT2 | 1.65V | 3.3V | 3.6V | 0.33mA | 42 | 2_10 |
| 3 | NC | | | | | | | |
| 4 | GND | Common Ground | | | | | | |
| 5 | GPIO1C | DIG_IN5/OUT5 | 1.65V | 3.3V | 3.6V | 0.33mA | 1 | 1_1 |
| 6 | GPIO1D | DIG_IN5/OUT6 | 1.65V | 3.3V | 3.6V | 0.33mA | 102 | 4_6 |
| 7 | NC | | | | | | | |
| 8 | VCC | Supply output | | 12V | | | | |

GPIO2:

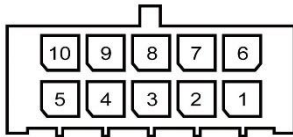
| Pin # | Signal | Description | Voltage | | | Current Max. | GPIO Kernel | GPIO Bank/IO |
|-------|--------|---------------|---------|------|------|--------------|-------------|--------------|
| | | | Min. | Typ. | Max. | | | |
| 1 | GPIO2A | DIG_IN1/OUT1 | 1.65V | 3.3V | 3.6V | 0.33mA | 164 | 6_4 |
| 2 | GPIO2B | DIG_IN2/OUT2 | 1.65V | 3.3V | 3.6V | 0.33mA | 165 | 6_5 |
| 3 | NC | | | | | | | |
| 4 | GND | Common Ground | | | | | | |
| 5 | GPIO2C | DIG_IN5/OUT5 | 1.65V | 3.3V | 3.6V | 0.33mA | 162 | 6_2 |
| 6 | GPIO2D | DIG_IN5/OUT6 | 1.65V | 3.3V | 3.6V | 0.33mA | 163 | 6_3 |
| 7 | NC | | | | | | | |
| 8 | VCC | Supply output | | 12V | | | | |

Header on TEP-1010-IMX6: Molex 43045-0800 (8-pin Micro-Fit 3.0).

Cable receptacle: Molex 43025-0800 (8-pin Micro-Fit 3.0) plug with crimp contact Molex 43030-0007.

3.15.2. Non-Galvanic Isolated Serial Port (RS-XXX) (optional)

The dual 4-wire non-galvanic isolated serial port are configured as follows: the primary and the secondary serial port can only be used as a standard RS-232.



RS-232 + RS-232:

| Pin # | Signal | Description | Device |
|-------|--------------|----------------------------------|---------|
| 1 | GND | Ground | |
| 2 | SERIAL1A_TXD | Port#1A Transmit data (output) | ttymxc0 |
| 3 | SERIAL1A_RXD | Port#1A Receive data (input) | ttymxc0 |
| 4 | SERIAL1A_RTS | Port#1A Request-to-send (output) | ttymxc0 |
| 5 | SERIAL1A_CTS | Port#1A Clear-to-send (input) | ttymxc0 |
| 6 | GND | Ground | |
| 7 | SERIAL1B_TXD | Port#1B Transmit data (output) | ttymxc1 |
| 8 | SERIAL1B_RXD | Port#1B Receive data (input) | ttymxc1 |
| 9 | SERIAL1B_RTS | Port#1B Request-to-send (output) | ttymxc1 |
| 10 | SERIAL1B_CTS | Port#1B Clear-to-send (input) | ttymxc1 |

NOTE: SERIAL1A port can act by default as serial debug console.

Header on TEP-1010-IMX6: Molex 43045-1000 (10-pin Micro-Fit 3.0).

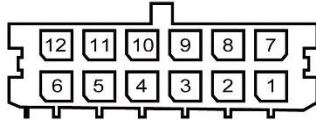
Cable receptacle: Molex 43025-1000 (10-pin Micro-Fit 3.0) plug with crimp contact Molex 43030-0007.

3.15.3. Non-Galvanic Isolated CAN Bus Connector (CANBus) (optional)

The non-galvanic isolated CAN Bus interfaces can be configured as follows: enabling or disabling of CAN Bus terminator resistor will require to open the device and adjust the internal SW1 Terminator Resistor DIP switch settings on the TEP I/O Expansion board. The SW1 DIP switch can be found at location “A” in chapter [3.15. Non-Galvanic Isolated Connectors \(TEP1010-IMX6x-Rxx-Exx-Lxxx-XS20-xxx-xxxx\) \(optional\)](#) of this manual.

SW1:

| Pin # | ON | OFF (default) |
|-------|----------------------------------|-----------------------------------|
| 1-8 | Enable CAN1A Terminator Resistor | Disable CAN1A Terminator Resistor |
| 2-7 | Enable CAN1A Terminator Resistor | Disable CAN1A Terminator Resistor |
| 3-6 | Enable CAN1B Terminator Resistor | Disable CAN1B Terminator Resistor |
| 4-5 | Enable CAN1B Terminator Resistor | Disable CAN1B Terminator Resistor |



CANBus

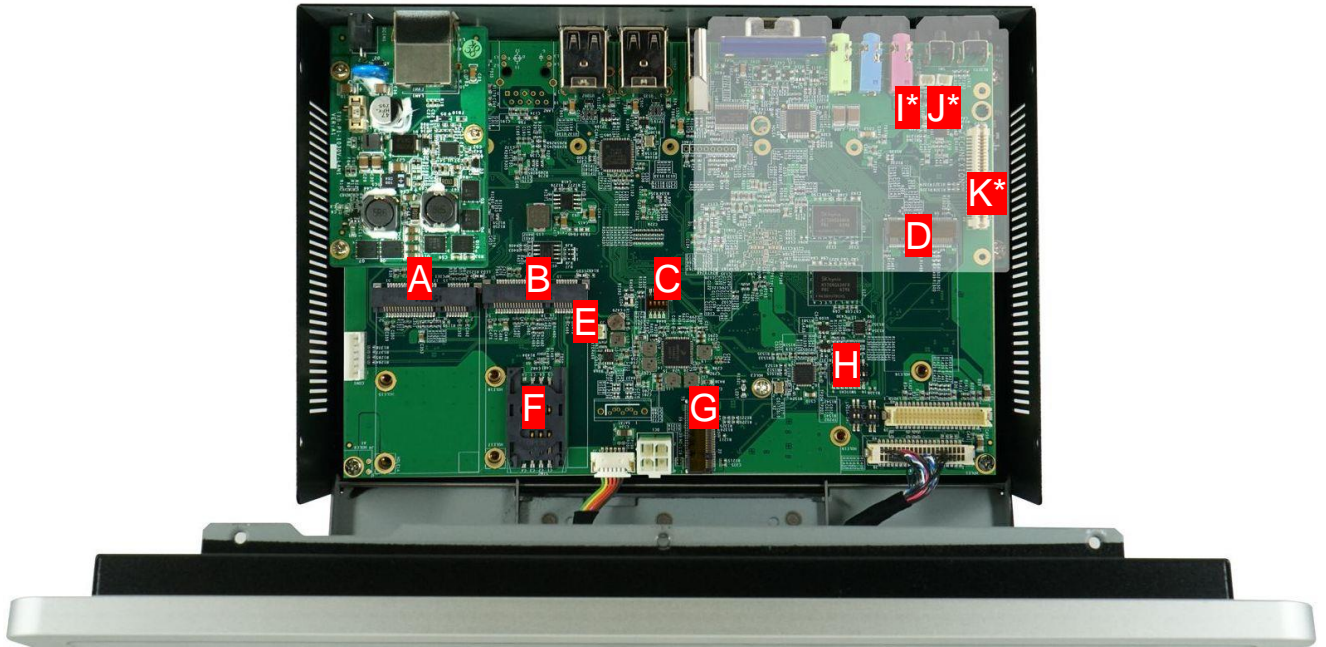
| Pin # | Signal | Description | Interface |
|-------|--------------|--|-----------|
| 1 | GND_CAN | Ground for CAN | |
| 2 | CAN1A_TERM_N | To enable CAN1A Termination, bridge with CAN1A_N | can0 |
| 3 | CAN1A_P | CAN Bus 1A high (-24~+24V) | can0 |
| 4 | CAN1A_N | CAN Bus 1A low (-24~+24V) | can0 |
| 5 | CAN1A_TERM_P | To enable CAN1A Termination, bridge with CAN1A_P | can0 |
| 6 | NC | | |
| 7 | GND_CAN | Ground for CAN | |
| 8 | CAN1B_TERM_N | To enable CAN1B Termination, bridge with CAN1B_N | can1 |
| 9 | CAN1B_P | CAN Bus 1B high (-24~+24V) | can1 |
| 10 | CAN1B_N | CAN Bus 1B low (-24~+24V) | can1 |
| 11 | CAN1B_TERM_P | To enable CAN1B Termination, bridge with CAN1B_P | can1 |
| 12 | NC | | |

Header on TEP-1010-IMX6: Molex 43045-1200 (12-pin Micro-Fit 3.0).

Cable receptacle: Molex 43025-1200 (12-pin Micro-Fit 3.0) plug with crimp contact Molex 43030-0007.

4. Internal Connectors and Expansion Options

Rear view (opened device) without the I/O Expansion module:



Internal Connectors and Switches:

| No. | Description | No. | Description |
|-----|----------------------------------|-----|--------------------------------|
| A | mini-PCIe connector (PCIe + USB) | G | M.2 KEY-B slot (SATA + USB) |
| B | mini-PCIe connector (USB) | H | SWITCH1 Boot mode DIP switch |
| C | SW2 Default Boot mode switch | I* | Internal R speaker connector |
| D | M.2 KEY-B slot (USB) | J* | Internal L speaker connector |
| E | RTC Battery connector | K* | I/O Expansion module connector |
| F | Mini-SIM card slot | | |

NOTE: Items marked with * are accessible only after removing the I/O Expansion module.

4.1. Mini-PCIe Connectors

The TEP-1010-IMX6 has two internal mini-PCIe connectors for full or half size cards: MPCIE1 and MPCIE2 (Marked A and B respectively). MPCIE1 connector supports PCIe and USB signals. On the other hand, MPCIE2 connector supports USB signals only. Mini-PCIe full size (30 x 50.95 mm) or half size (30 x 26.8 mm) cards are supported.

4.2. Mini-SIM Card slot

The TEP-1010-IMX6 features an internal Mini-SIM card slot for use by 3G/4G/LTE wireless module (Marked G).

NOTE: This card slot can be only used by a mini-PCIe 3G/4G/LTE module installed into the MPCIE2 connector (Marked B). No mini-PCIe 3G/4G LTE module is included in this device (must be purchased separately, not sold by TechNexion).

4.3. M.2 KEY-B Slots

The TEP-1010-IMX6 has two internal M.2 connectors: M2-1 and M2-2 (Marked H and D respectively). M2-1 connector supports either SATA and USB signals (TEP1010-**IMX6Q**-Rxx-Exx-Lxxx-xxxx-xxx-xxxx) or USB signals only (TEP1010-**IMX6S**-Rxx-Exx-Lxxx-xxxx-xxx-xxxx or TEP1010-**IMX6U**-Rxx-Exx-Lxxx-xxxx-xxx-xxxx). On the other hand, M2-2 connector supports USB signals only. M.2 cards in the M.2 KEY-B 2242 (22 x 42 mm) form factor are supported.

4.4. SW2 Default Boot Mode Switch

The TEP-1010-IMX6 has an internal SW2 Default Boot Mode switch (Marked C).

| Pin # | eMMC (default) | microSD | SATA |
|-------|----------------|---------|------|
| 1-8 | ON | ON | OFF |
| 2-7 | ON | OFF | ON |
| 3-6 | ON | OFF | - |
| 4-5 | ON | OFF | - |

4.5. SWITCH1 Boot Mode DIP Switch

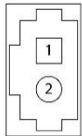
The TEP-1010-IMX6 has an internal SWITCH1 Default Boot Mode DIP switch for S1 boot select button (Marked I).

| Pin # | eMMC | microSD (default) | SATA* |
|-------|------|-------------------|-------|
| 1-16 | OFF | ON | OFF |
| 2-15 | OFF | ON | - |
| 3-14 | ON | OFF | ON |
| 4-13 | ON | OFF | - |
| 5-12 | ON | OFF | - |
| 6-11 | OFF | OFF | OFF |
| 7-10 | ON | ON | OFF |
| 8-9 | OFF | OFF | OFF |

NOTE: SATA boot mode is available on the TEP1010-**IMX6Q**-Rxx-Exx-Lxxx-xxxx-xxx-xxxx only.

4.6. RTC Battery Connector

The TEP-1010-IMX6 features an internal RTC backup battery connector (Marked E).

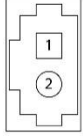


| Pin # | Signal | Description |
|-------|---------|---|
| 1 | RTC_VCC | 3V (connect to standard CR2032 battery) |
| 2 | GND | Ground |

Header on TEP-1010-IMX6: Molex 53047-0210 (1.25mm Pitch PicoBlade Wire-to-Board Header).
 Cable receptacle: Molex 051021-8602 (1.25mm Pitch PicoBlade Wire-to-Wire and Wire-to-Board Housing) plug with crimp contact Molex 50058-8000.
 Battery P/N: KTS BCR2032H14.0AM1XB.

4.7. Internal Stereo Speaker Connectors

The TEP-1010-IMX6 has two internal stereo speaker connectors to connect to two optional LEFT and RIGHT speakers (Marked K and J respectively). The signal is pre-amplified with a 2W Texas Instruments TPA2012D2 Class-D stereo audio amplifier.



LEFT Speaker connector (Marked K).

| Pin # | Signal | Description |
|-------|---------|-----------------------------------|
| 1 | S_OUTL+ | LEFT Speaker Positive Signal |
| 2 | S_OUTL- | LEFT Speaker Analog Ground Signal |

RIGHT Speaker connector (Marked J).

| Pin # | Signal | Description |
|-------|---------|------------------------------------|
| 1 | S_OUTR+ | RIGHT Speaker Positive Signal |
| 2 | S_OUTR- | RIGHT Speaker Analog Ground Signal |

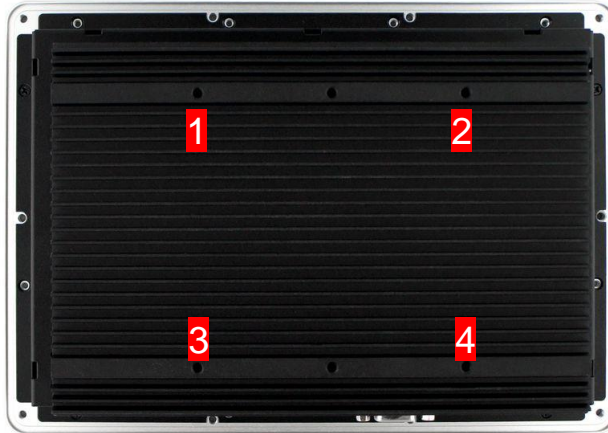
Header on TEP-1010-IMX6: Molex 53047-0210 (1.25mm Pitch PicoBlade Wire-to-Board Header).
Cable receptacle: Molex 051021-8602 (1.25mm Pitch PicoBlade Wire-to-Wire and Wire-to-Board Housing) plug with crimp contact Molex 50058-8000.

5. Mounting

This section describes the mounting procedures for the TEP-1010-IMX6. The material in area of the mounting must provide sufficient strength for safe mounting of this device.

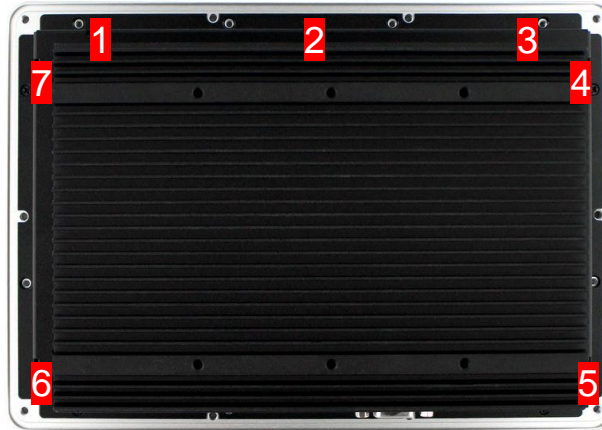
5.1. VESA Mounting

The TEP-1010-IMX6 is compatible with the VESA MIS-D Standard 100*100mm hole pattern. There are 4 VESA MIS-D (M4) mounting holes on the rear side of the device. M4 screw holes are a depth of 6mm.



5.2. Rear Mounting and Mounting Clips Installation

There are 7 mounting clips required for rear mounting.



Please follow the steps below to secure the clips. Prepare mounting hook, post and screw (M3) (Step 1). Locate all removable tabs on the rear side of your device and use pincers or pliers to remove the tabs (Step 2-3). Press the mounting clip into the holes at an angle and slowly straighten it (Step 4-5). Then tighten the screw to the surface (Step 6). Repeat the steps for all clips required to secure your device.



5.3. Surface Mounting and O-ring Installation

There are 10 mounting holes (M4) on the rear side of the device required for surface mounting. M4 screws with at least 6mm head-to-tip length are required to secure this device.



Please follow the steps below to properly install the waterproof rubber O-ring. Prepare your device and O-ring (Step 1-2). First, align the O-ring with the groove and press the O-ring into the corners of the O-ring groove (Step 3-4). Then, press it into the center (Step 5). Finally, stretch it uniformly around the O-ring groove (Step 6). Do not pull from one side, and make sure that you stretch it as little as possible.



6. Ordering Information

The TEP-1010-IMX6 is available in several configurations. Please contact your TechNexion sales contact window or distributor for options and availability details.

6.1. Custom Part Number Rule

The TEP-1010-IMX6 can be ordered in custom tailored configuration to meet special application requirements and conditions according to the following custom part number creation rules. Custom part numbers carry minimum order quantities (MOQ). Please connect with your TechNexion distributor or account manager for conditions and availability. Part number format:

TEP1010-IMX6x-Rxx-Exx-Lxxx-Xxxx-xxx-xxxx-xxxx

| Interface | Code | Description |
|-------------------|-------|--|
| Processor | IMX6S | NXP i.MX6Solo |
| | IMX6U | NXP i.MX6DualLite |
| | IMX6Q | NXP i.MX6Quad |
| Memory | R05 | 512MB DDR3 |
| | R10 | 1GB DDR3 |
| | R20 | 2GB DDR3 |
| Storage | E04 | eMMC 4GB |
| | E08 | eMMC 8GB |
| | EXX | eMMC other capacity |
| Power Expansion | L112 | TXR-P1-12V-LAN1 (12V 3A) |
| | L130 | TXR-P1-1030V-LAN1 (8-36V 5A) |
| | LPOE | TXR-P1-12V-POE1 (12V 3A) or (PoE 802.3at) |
| I/O Expansion | - | - |
| | XS20 | 2x RS-232 + 2x CAN + 8x GPIO |
| | XG20 | 2x RS-232 + 2x CAN + 8x GPIO (Galvanic Isolated) |
| Internal Speaker | - | - |
| | SPK | 2x 2W/8Ω Stereo Speaker |
| Wi-Fi / Bluetooth | - | - |
| | 9377 | Qualcomm QCA9377 802.11a/b/g/n/ac (2.4 + 5GHz) + Bluetooth 5 |
| Custom ID | XXXX | Custom Part number ID for customized software loader and special component (BOM) |

6.2. Standard Package Contents



| Item | Partnumber | Description |
|------|---------------|--|
| 1 | TEP-1010-IMX6 | 10 inch PoE HMI PCAP touch system with NXP i.MX6 |
| 2 | Accessoires | 7x mounting hooks |
| | | 7x long screws (M3) |
| | | 7x mounting posts |
| | | 2x hexagonal bolt |
| | | 2x mini-PCIe screw (M2) |
| | | 2x screw (M3) |
| | | 2x plastic washer |
| | | 1x rubber O-ring |
| | | 1x DC power latch cable (2-pin Micro-Fit 3.0) |

NOTE: Pack contents might vary depending on your ordered configuration.

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